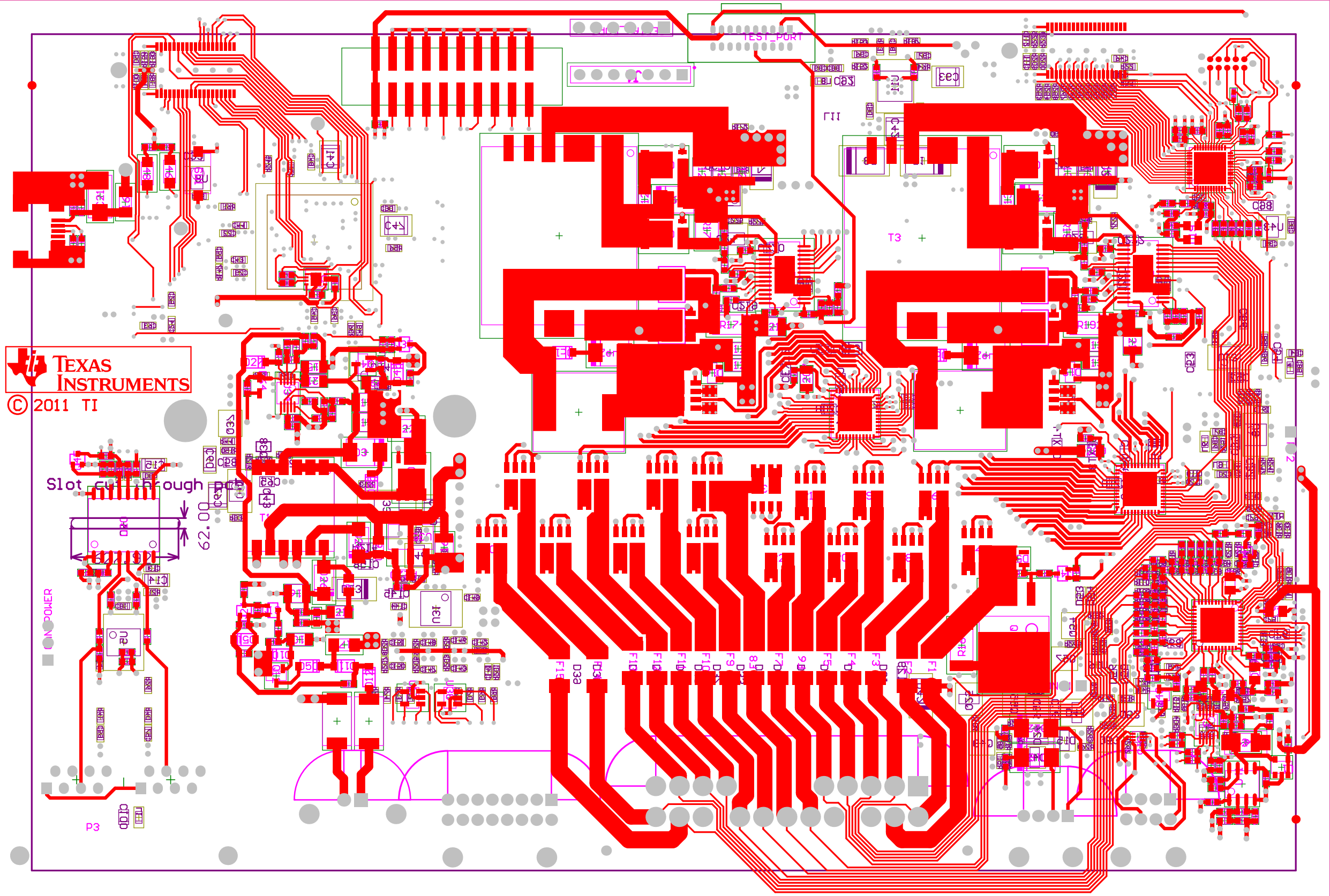


Layer Stack Up Detail for: EM1401_RevA2.PcbDoc			
Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	<.GTS>		Solder Resist
Top Layer	<.GTL>	2.8mil	FR-4
MidLayer1	<.G1>	2.8mil	
MidLayer2	<.G2>	2.8mil	
MidLayer3	<.G3>	2.8mil	
MidLayer4	<.G4>	2.8mil	
Bottom Layer	<.GBL>	2.8mil	FR-4
Bottom Solder Mask	<.GBS>		
			Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



ALL ARTWORK VIEWED FROM TOP SIDE	
BOARD NAME	BMS EM1401 Rev A2 (TIDA-00239)
ARTWORK #	600748 A2
LAYER NAME	Top Layer
PLOT NAME	Top Layer
PRINT DATE	5/22/2014 12:36:22 PM

PROJECT TITLE:
BMS EM1401 Rev A2 (TIDA-00239)

DESIGNED FOR:

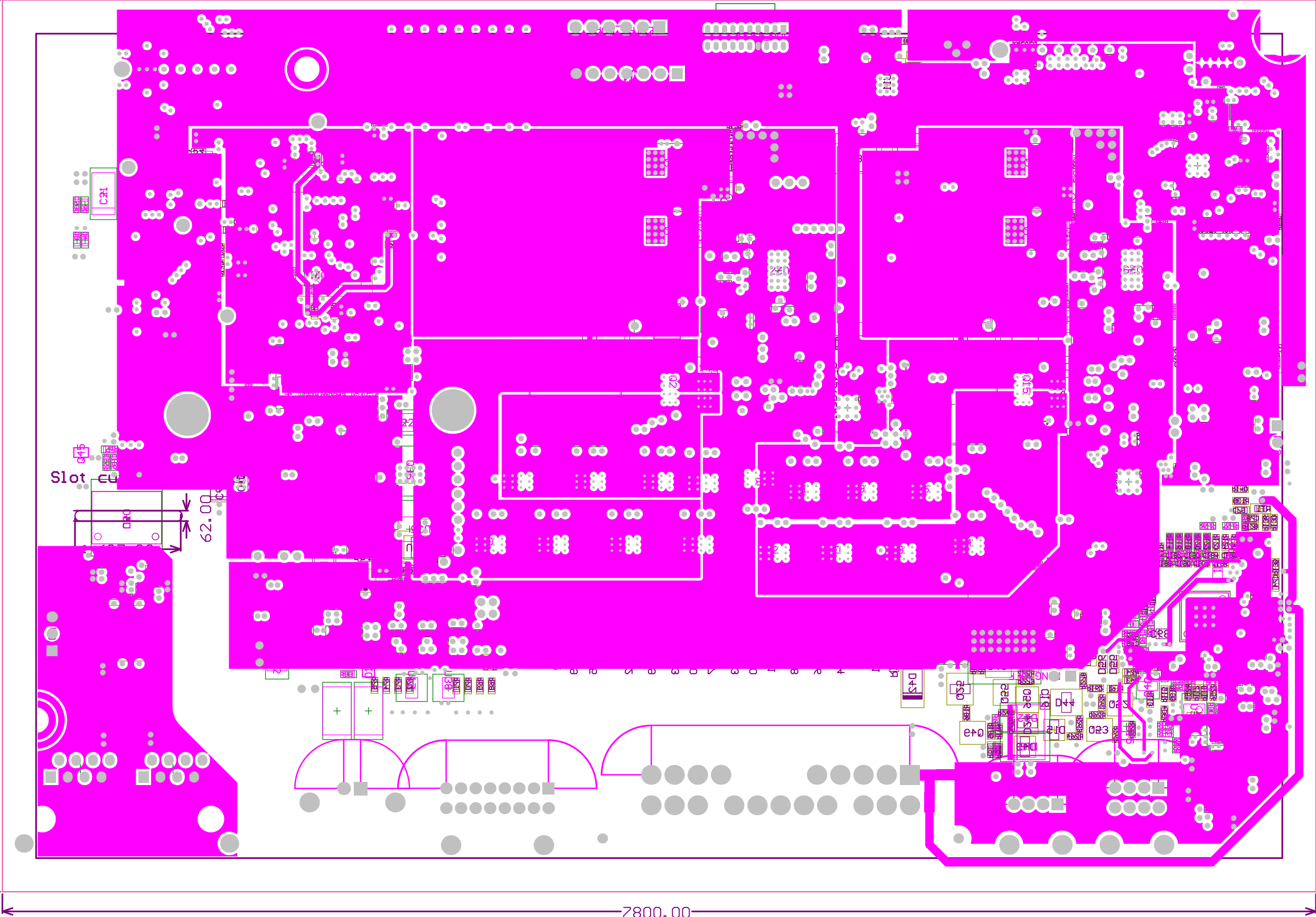
REV: A2	PRINT DATE: 5/22/2014	PADC NUMBER:	FAB DRAWING NUMBER: 551600748
FILE NAME: EM1401_RevA2.PcbDoc		SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009

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Layer Stack Up Detail for: EM1401_RevA2.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	<.GTS>		Solder Resist
Top Layer	<.GTL>	2.8mil	FR-4
MidLayer1	<.G1>	2.8mil	FR-4
MidLayer2	<.G2>	2.8mil	FR-4
MidLayer3	<.G3>	2.8mil	FR-4
MidLayer4	<.G4>	2.8mil	FR-4
Bottom Layer	<.GBL>	2.8mil	FR-4
Bottom Solder Mask	<.GBS>		Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



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ALL ARTWORK VIEWED FROM TOP SIDE

BOARD NAME	BMS EM1401 Rev A2 <TIDA-00239>
ARTWORK #	600748 A2
LAYER NAME	MidLayer1
PLOT NAME	MidLayer1
PRINT DATE	5/22/2014 12:36:26 PM

PROJECT TITLE:
BMS EM1401 Rev A2 <TIDA-00239>

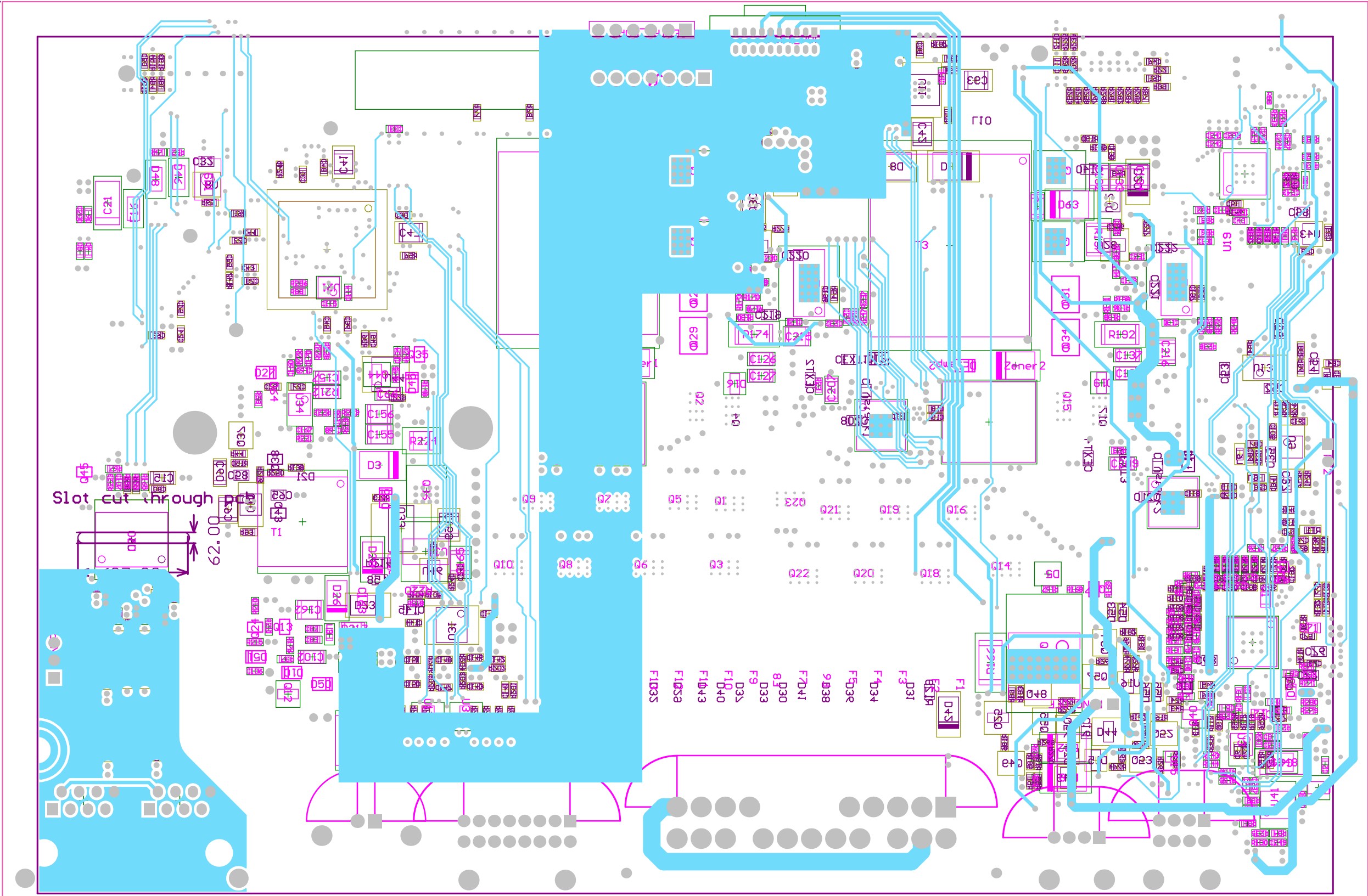
DESIGNED FOR:

REV: A2	PRINT DATE: 5/22/2014
FILE NAME: EM1401_RevA2.PcbDoc	

PADC NUMBER: 551600748	FAB DRAWING NUMBER: 551600748
SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: EM1401_RevA2.PcbDoc			
Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	<.GTS>		Solder Resist
Top Layer	<.GTL>	2.8mil	FR-4
MidLayer1	<.G1>	2.8mil	FR-4
MidLayer2	<.G2>	2.8mil	FR-4
MidLayer3	<.G3>	2.8mil	FR-4
MidLayer4	<.G4>	2.8mil	FR-4
Bottom Layer	<.GBL>	2.8mil	FR-4
Bottom Solder Mask	<.GBS>		Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



ALL ARTWORK VIEWED FROM TOP SIDE	
BOARD NAME	BMS EM1401 Rev A2 <TIDA-00239>
ARTWORK #	600748 A2
LAYER NAME	MidLayer2
PLOT NAME	MidLayer2
PRINT DATE	5/22/2014 12:36:31 PM

PROJECT TITLE:
BMS EM1401 Rev A2 <TIDA-00239>

DESIGNED FOR:

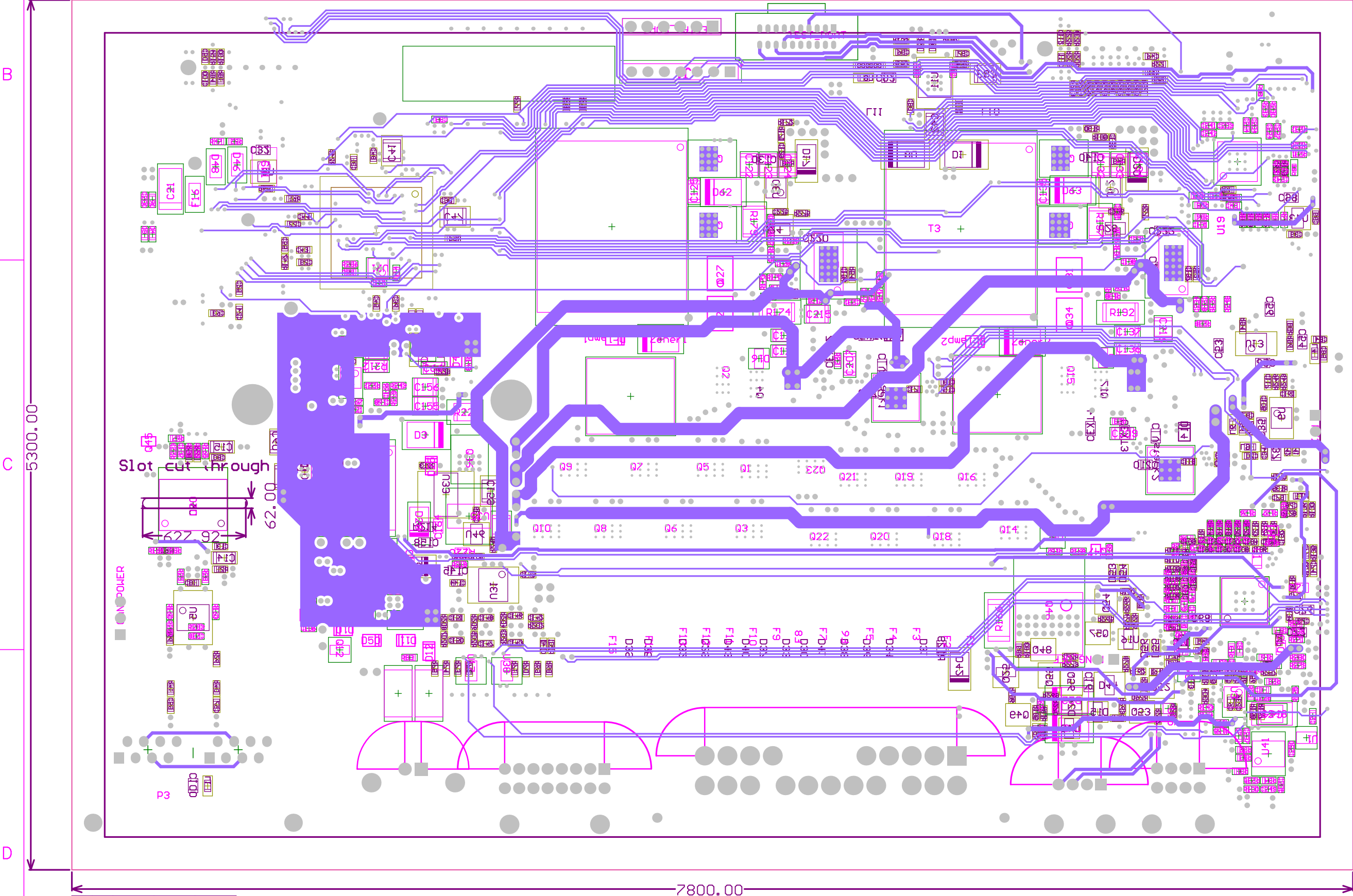
REV: A2	PRINT DATE: 5/22/2014	PADC NUMBER:	FAB DRAWING NUMBER: 551600748
FILE NAME: EM1401_RevA2.PcbDoc		SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009

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Layer Stack Up Detail for: EM1401_RevA2.PcbDoc			
Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	<.GTS>		Solder Resist
Top Layer	<.GTL>	2.8mil	FR-4
MidLayer1	<.G1>	2.8mil	
MidLayer2	<.G2>	2.8mil	
MidLayer3	<.G3>	2.8mil	
MidLayer4	<.G4>	2.8mil	
Bottom Layer	<.GBL>	2.8mil	FR-4
Bottom Solder Mask	<.GBS>		
			Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



	
ALL ARTWORK VIEWED FROM TOP SIDE	
BOARD NAME	BMS EM1401 Rev A2 <TIDA-00239>
ARTWORK #	600748 A2
LAYER NAME	MidLayer3
PLOT NAME	MidLayer3
PRINT DATE	5/22/2014 12:36:36 PM

PROJECT TITLE:
BMS EM1401 Rev A2 <TIDA-00239>

DESIGNED FOR:

REV: A2	PRINT DATE: 5/22/2014
FILE NAME: EM1401_RevA2.PcbDoc	

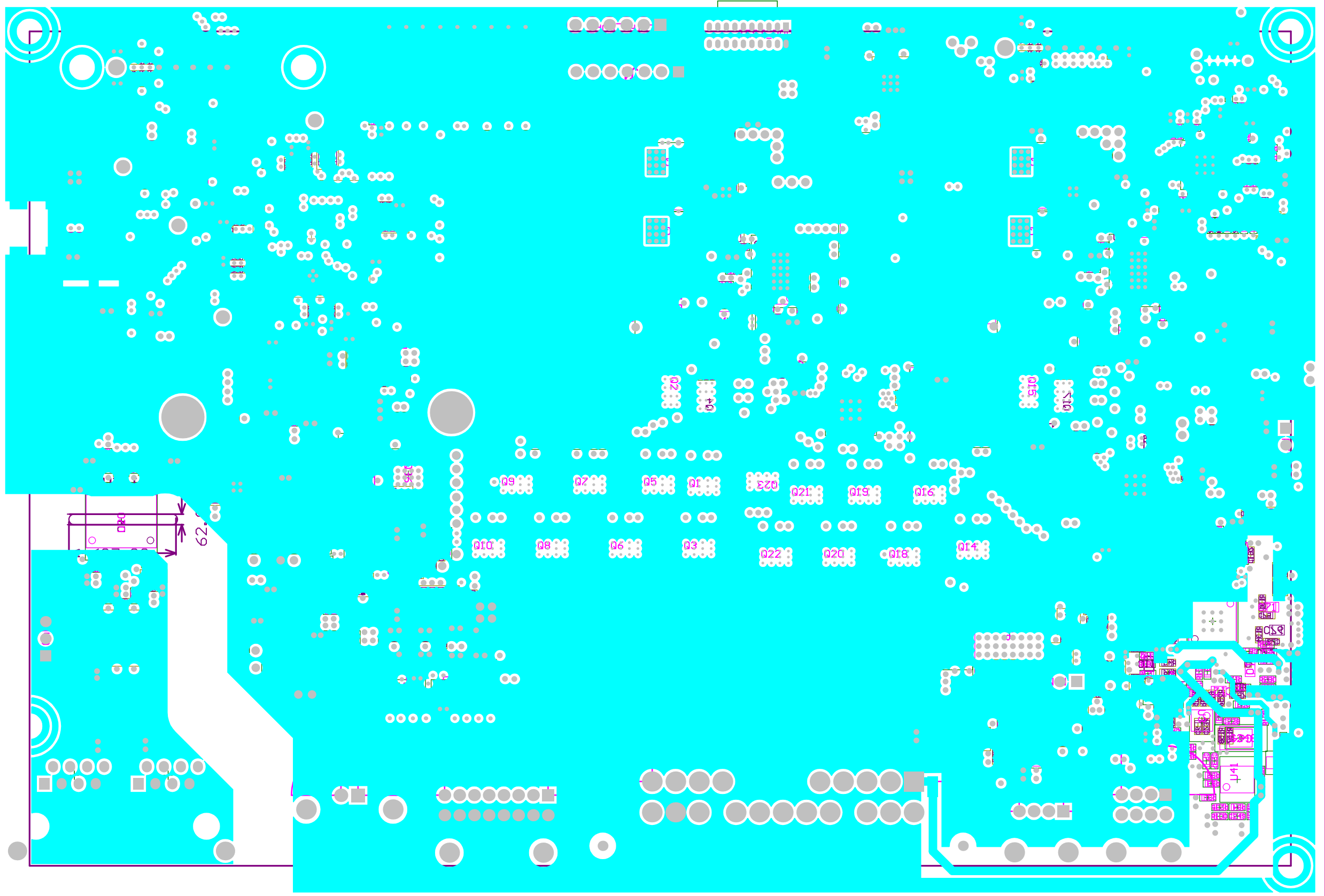
PADC NUMBER: 551600748	FAB DRAWING NUMBER: 551600748
SCALE: 1.00	
ALTIM DESIGNER VERSION: 10.0.0.27009	

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Layer Stack Up Detail for: EM1401_RevA2.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	<.GTS>		Solder Resist
Top Layer	<.GTL>	2.8mil	FR-4
MidLayer1	<.G1>	2.8mil	
MidLayer2	<.G2>	2.8mil	
MidLayer3	<.G3>	2.8mil	
MidLayer4	<.G4>	2.8mil	
Bottom Layer	<.GBL>	2.8mil	FR-4
Bottom Solder Mask	<.GBS>		Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



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ALL ARTWORK VIEWED FROM TOP SIDE

BOARD NAME	BMS EM1401 Rev A2 <TIDA-00239>
ARTWORK #	600748 A2
LAYER NAME	MidLayer4
PLOT NAME	MidLayer4
PRINT DATE	5/22/2014 12:36:41 PM

PROJECT TITLE:
BMS EM1401 Rev A2 <TIDA-00239>

DESIGNED FOR:

REV: A2	PRINT DATE: 5/22/2014
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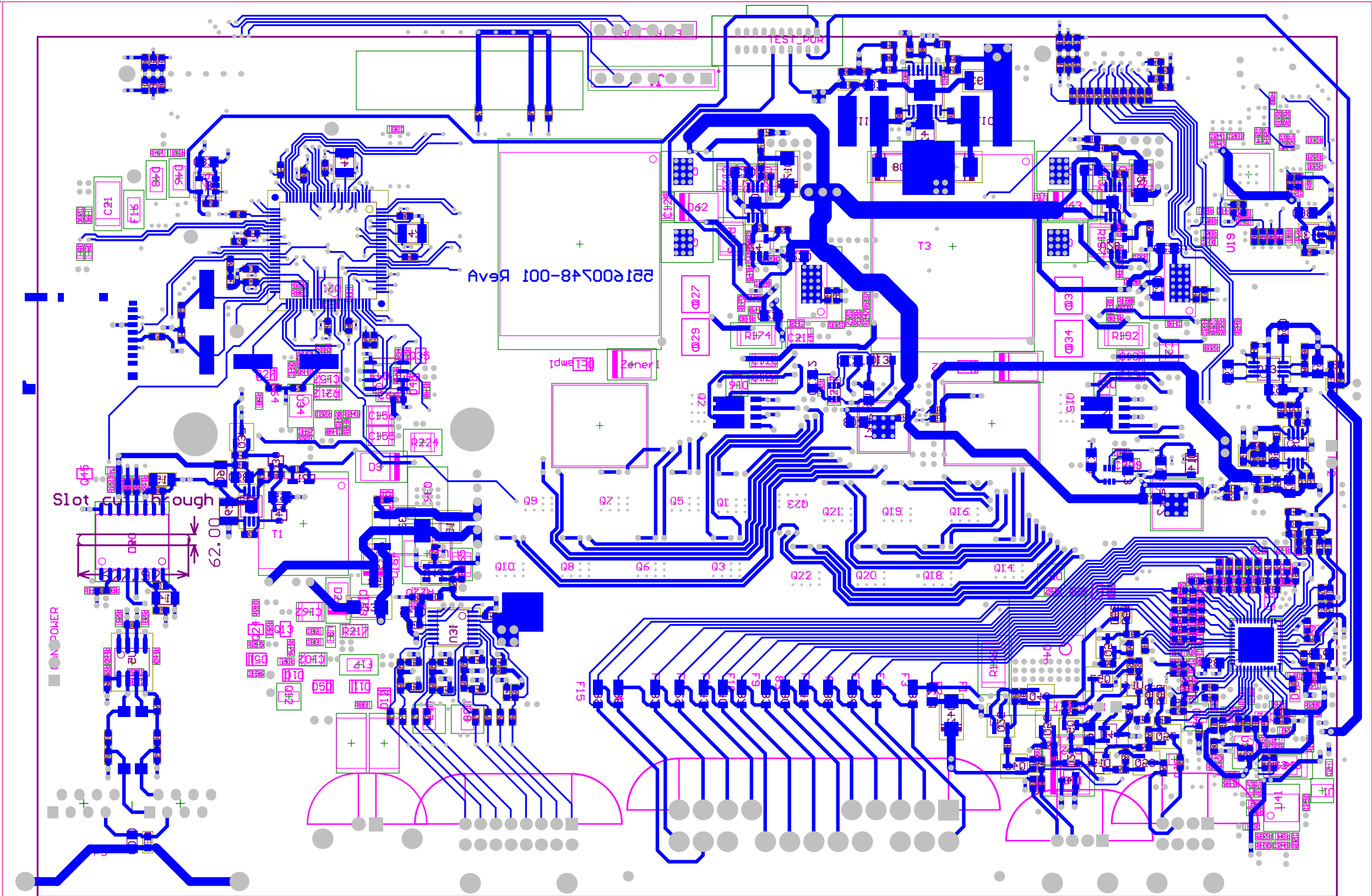
FILE NAME:
EM1401_RevA2.PcbDoc

PADC NUMBER: 	FAB DRAWING NUMBER: 551600748
SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: EM1401_RevA2.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	2.8mil	FR-4
MidLayer1	(.G1)	2.8mil	FR-4
MidLayer2	(.G2)	2.8mil	FR-4
MidLayer3	(.G3)	2.8mil	FR-4
MidLayer4	(.G4)	2.8mil	FR-4
Bottom Layer	(.GBL)	2.8mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD NAME	BMS EM1401 Rev A2 (TIDA-00239)
ARTWORK #	600748 A2
LAYER NAME	Bottom Layer
PLOT NAME	Bottom Layer
PRINT DATE	5/22/2014 12:36:45 PM

PROJECT TITLE:
BMS EM1401 Rev A2 (TIDA-00239)

DESIGNED FOR:

REV: A2	PRINT DATE: 5/22/2014
FILE NAME: EM1401_RevA2.PcbDoc	

PADC NUMBER: 551600748	FAB DRAWING NUMBER: 551600748
SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009

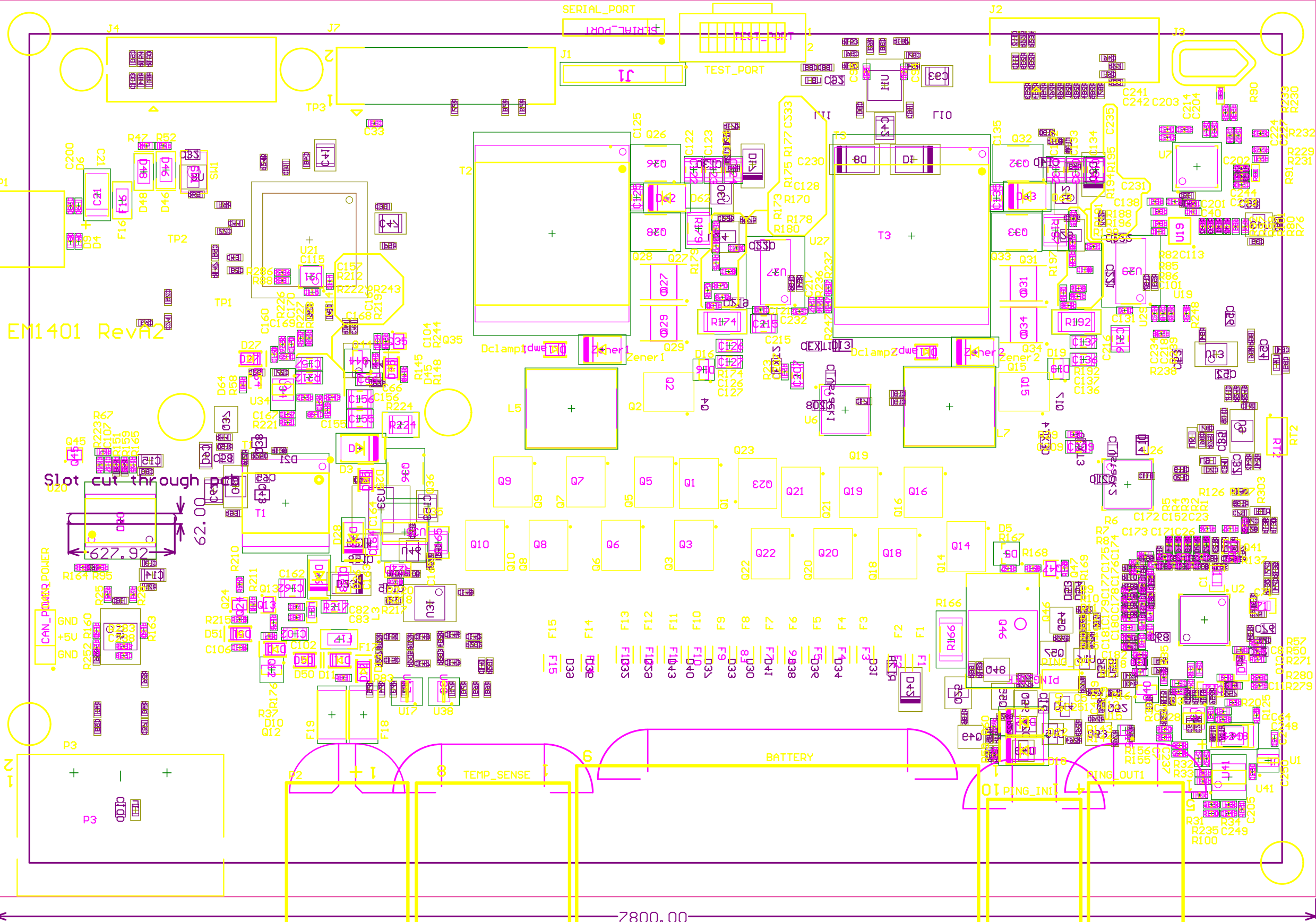
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Layer Stack Up Detail for: EM1401_RevA2.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	2.8mil	FR-4
MidLayer1	(.G1)	2.8mil	FR-4
MidLayer2	(.G2)	2.8mil	FR-4
MidLayer3	(.G3)	2.8mil	FR-4
MidLayer4	(.G4)	2.8mil	FR-4
Bottom Layer	(.GBL)	2.8mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



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ALL ARTWORK VIEWED FROM TOP SIDE

BOARD NAME	BMS EM1401 Rev A2 (TIDA-00239)
ARTWORK #	880 600748 A2
LAYER NAME	Top Silkscreen Overlay
PLOT NAME	Top Silkscreen Overlay
PRINT DATE	5/22/2014 12:36:50 PM

PROJECT TITLE:
BMS EM1401 Rev A2 (TIDA-00239)

DESIGNED FOR:

REV:
A2

FILE NAME:
EM1401_RevA2.PcbDoc

PRINT DATE:
5/22/2014

PADC NUMBER:
SCALE: 1.00

FAB DRAWING NUMBER:
551600748

ALTUM DESIGNER VERSION:
10.0.0.27009

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Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	2.8mil	FR-4
MidLayer1	(.G1)	2.8mil	
MidLayer2	(.G2)	2.8mil	FR-4
MidLayer3	(.G3)	2.8mil	FR-4
MidLayer4	(.G4)	2.8mil	FR-4
Bottom Layer	(.GBL)	2.8mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



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ALL ARTWORK VIEWED FROM TOP SIDE

BOARD NAME	BMS_EM1401_Rev_A2 (TIDA-00239)
ARTWORK #	880 600748 A2
LAYER NAME	MPC8548E Top Copper Bottom
PLOT NAME	Bottom Silkscreen Overlay
PRINT DATE	5/22/2014 12:36:55 PM

PROJECT TITLE:
BMS EM1401 Rev A2 (TIDA-00239)

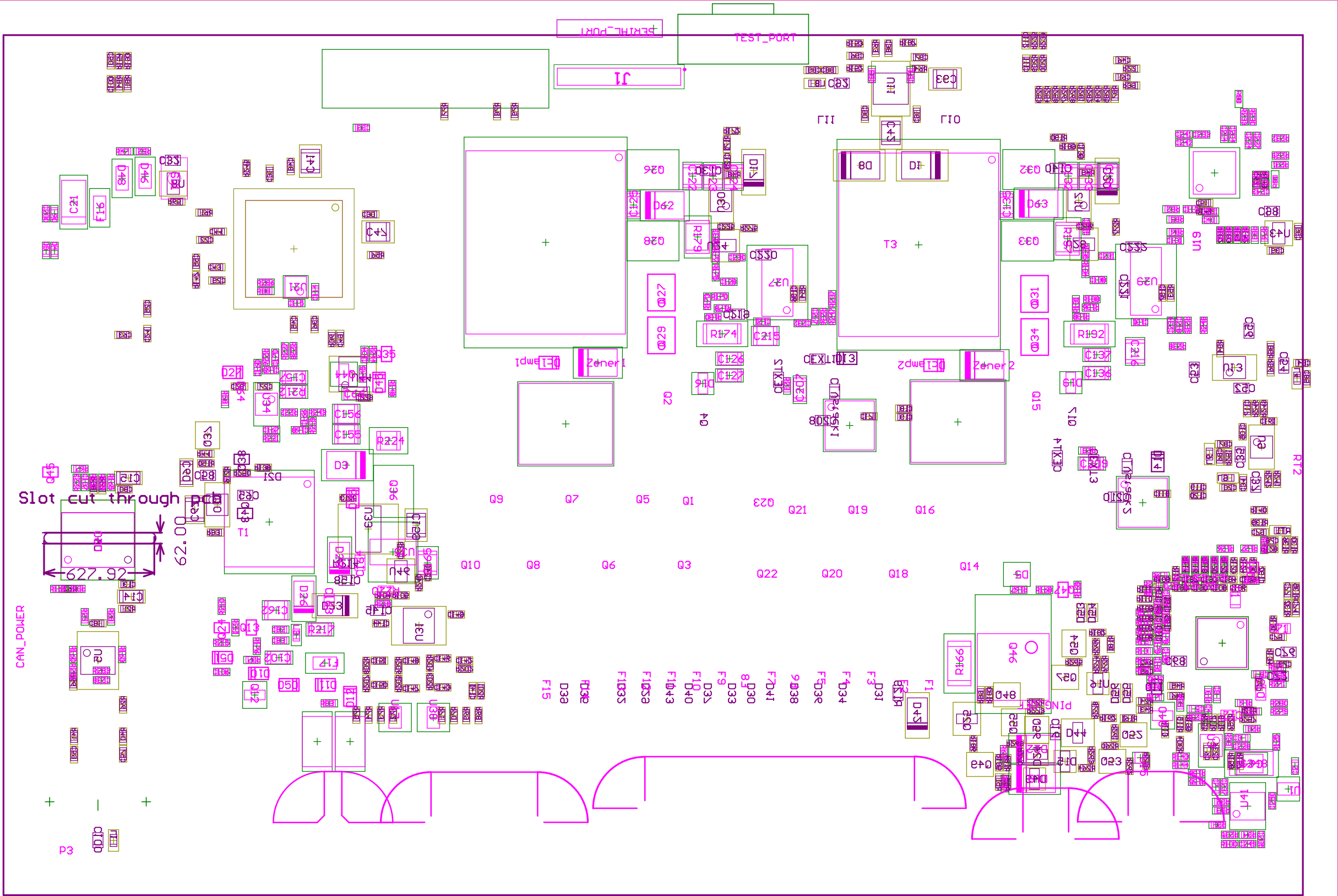
DESIGNED FOR:

REV: A2	PRINT DATE: 5/22/2014	PADC NUMBER:	FAB DRAWING NUMBER: 551600748
FILE NAME: EM1401_RevA2.PcbDoc		SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: EM1401_RevA2.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	<.GTS>		Solder Resist
Top Layer	<.GTL>	2.8mil	FR-4
MidLayer1	<.G1>	2.8mil	FR-4
MidLayer2	<.G2>	2.8mil	FR-4
MidLayer3	<.G3>	2.8mil	FR-4
MidLayer4	<.G4>	2.8mil	FR-4
Bottom Layer	<.GBL>	2.8mil	FR-4
Bottom Solder Mask	<.GBS>		Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD NAME	BMS EM1401 Rev A2 (TIDA-00239)
ARTWORK #	600748 A2
LAYER NAME	M5 Assembly Top
PLOT NAME	M5 Assembly Top
PRINT DATE	5/22/2014 12:37:00 PM

PROJECT TITLE:
BMS EM1401 Rev A2 (TIDA-00239)

DESIGNED FOR:

REV:
A2

FILE NAME:
EM1401_RevA2.PcbDoc

PRINT DATE:
5/22/2014

PADC NUMBER:

SCALE: 1.00

FAB DRAWING NUMBER:
551600748

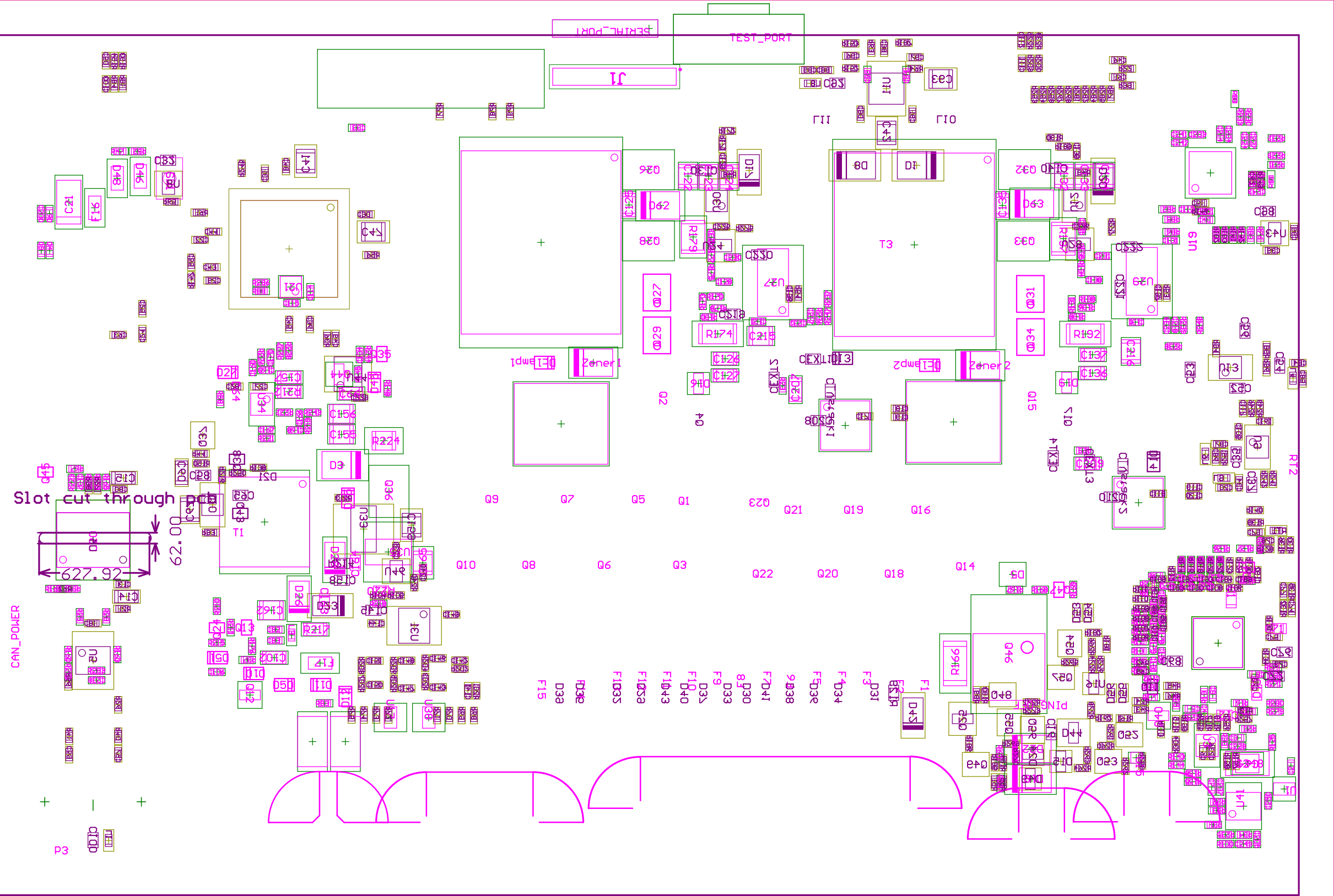
ALTUM DESIGNER VERSION:
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Layer Stack Up Detail for: EM1401_RevA2.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	<.GTS>		Solder Resist
Top Layer	<.GTL>	2.8mil	FR-4
MidLayer1	<.G1>	2.8mil	FR-4
MidLayer2	<.G2>	2.8mil	FR-4
MidLayer3	<.G3>	2.8mil	FR-4
MidLayer4	<.G4>	2.8mil	FR-4
Bottom Layer	<.GBL>	2.8mil	FR-4
Bottom Solder Mask	<.GBS>		Solder Resist

Stack up to be specified by manufacturer for best fit for 62mil board



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD NAME	BMS EM1401 Rev A2 (TIDA-00239)
ARTWORK #	600748 A2
LAYER NAME	M6 Assembly Bottom
PLOT NAME	M6 Assembly Bottom
PRINT DATE	5/22/2014 12:37:05 PM

PROJECT TITLE:
BMS EM1401 Rev A2 (TIDA-00239)

DESIGNED FOR:

REV:
A2

FILE NAME:
EM1401_RevA2.PcbDoc

PRINT DATE:
5/22/2014

PADC NUMBER:

SCALE: 1.00

FAB DRAWING NUMBER:
551600748

ALTUM DESIGNER VERSION:
10.0.0.27009

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